Display Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 240320P1 VMX-PW-N

3,4" TFT

Product Specification

Ver.: 0

Revision History

Revision	Date	Originator	Detail	Remarks
0	17.10.2024	LQ	Initial Release	-

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	3.4"	-
LCD type	IPS TFT	-
Display Mode	Transmissive /Normally Black	-
Resolution	240 RGB x 320	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	53.91(H) x 74.33(V) x 1.99(T) (Note1)	mm
Active Area	(51.27) (H) x (68.36) (V)	mm
Pixel Size	0.213 x 0.213	mm
Pixel Arrangement	RGB Vertical Stripe	-
Display Colors	16.7 Million	-
Interface	4-Wire SPI	-
With or without touch panel	Without	-
Driver IC	ST7789P3 (Sitronix)	-
Operating Temperature	-30°C to +80°C	°C
Storage Temperature	-30°C to +85°C °C	
Weight	~ 31	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDD	-0.3	4.6	V
Storage Temperature	T _{STG}	-30	+80	°C
Operating Temperature	T _{OP}	-30	+85	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10°C, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage	VDD	2.4	2.8	3.3	V
Logic Low Input Voltage	VIL	GND	-	0.3*VDD	V
Logic High input Voltage	ViH	0.7*VDD	-	VDD	V
Logic Low Output Voltage	Vol	GND	-	0.2*VDD	V
Logic High Output Voltage	Voh	0.8*VDD	-	VDD	V
Current Consumption All White	I _{DD}	-	(12)	-	mA

5. Backlight Characteristics

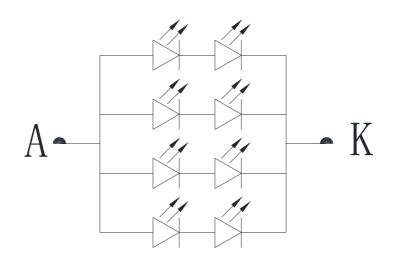
Item	Symbol	Symbol Condition		Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I _F =20mA/LED	5.6	6.0	6.6	V
Forward Current	lF	Ta=25 °C, V _F =3.0V/LED	-	80	-	mA
Power Dissipation	PD	PD 480 - mW				mW
Uniformity	Avg	Avg 80 - %				%
LED Lifetime (25°C)	-	30,000 - Hrs				
Drive Method	Constant Current					
LED Configuration	3	8 White LEDs (2 LEDs in st	ring and 4	groups i	n parallel)

Note1: LED Lifetime defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow,

at Ta=25°C \pm 2°C, 60%RH \pm 5%, I_F=20mA/LED.

5.1. Backlighting Circuit



6. Optical Characteristics

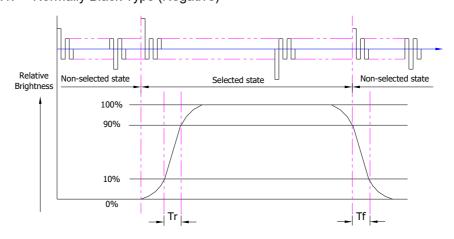
6.1. Optical Characteristics

Ta=25°C, VDD=2.8V

			0 1		S	pecificatio	n	11.24
	Item		Symbol	Condition	Min.	Тур.	Max.	Unit
	Luminar	nce on						
<u> </u>	$TFT(I_f = 20$	mA/LED)	Lv	Normally	400	500	-	cd/m²
po	Contrast Rat	io(See 7.3)	CR	viewing angle $\theta x = \phi y = 0^{\circ}$	1000	1200	-	
Backlight On (Transmissive Mode)	Response Time (See 6.2)		TR+TF	υχ = ψτ =υ	1	30	35	ms
nis		Red			(0.593)	(0.643)	(0.693)	
nsr		Neu	YR		(0.302)	(0.352)	(0.402)	
Tra	Chromoticity	Green	XG		(0.267)	(0.317)	(0.367)	
) u	Chromaticity Transmissive	010011	YG		(0.594)	(0.644)	(0.694)	
h C	(See 6.5)	Blue	Хв		(0.097)	(0.147)	(0.197)	
	(See 0.3) Blue		Yв		(0.064)	(0.114)	(0.164)	
ack		White	Xw		(0.254)	(0.304)	(0.354)	
a		VVIIILE	Yw		(0.290)	(0.340)	(0.390)	
	Viewing	Horizontal	θx+		75	80	-	
	Angle	i ionzoniai	θх-	Center CR≥10	75	80	-	Deg.
	(See 6.4)	Vertical	фҮ+	Joniel Oli-10	75	80	-	Dog.
	(See 6.4) Vertical		φY-		75	80	-	
	NTSC Ratio	o(Gamut)			60	65	-	%

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

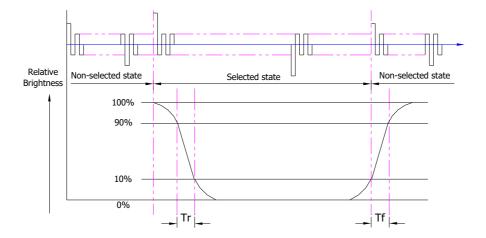


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

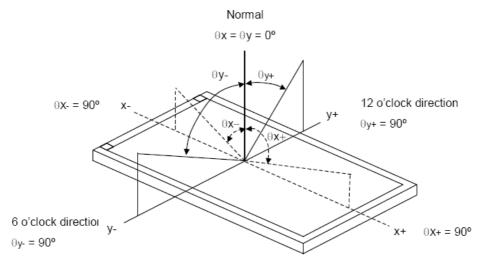
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent	
Measuring Point Diameter	3mm//1mm	
Measuring Point Location	Active Area centre point	
Toot nottorn	A: All Pixels white	
Test pattern	B: All Pixel black	
Contrast setting	Maximum	

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

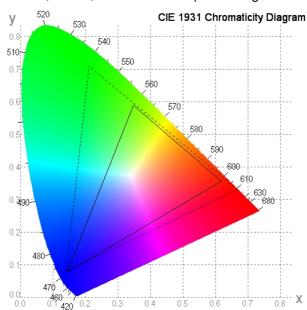
6.4. Definition of Viewing Angles



Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R, G, B and W are defined by (x, y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%



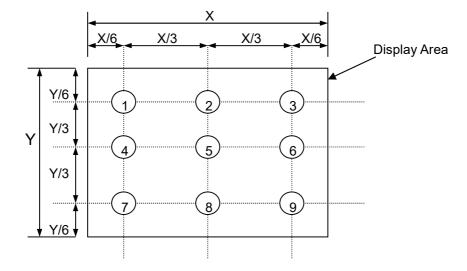
Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

6.6. Definition of Surface Luminance, Uniformity and Transmittance

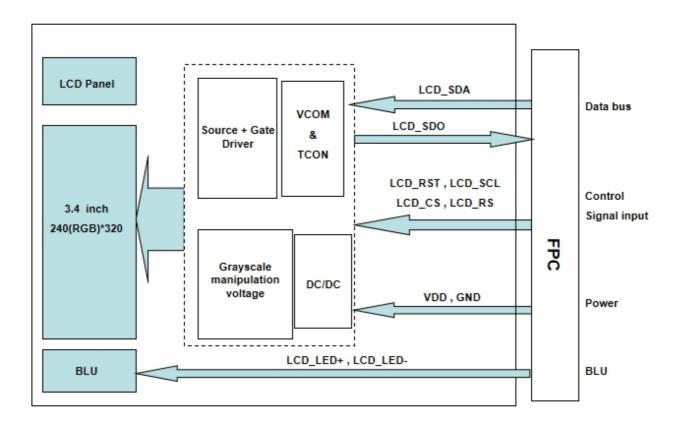
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance: L_V = average (L_{P1} : L_{P9})
- 6.6.2. Uniformity = Minimal $(L_{P1}:L_{P9})$ / Maximal $(L_{P1}:L_{P9})$ * 100%
- 6.6.3. Transmittance = L_V on LCD / L_V on Backlight * 100%

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

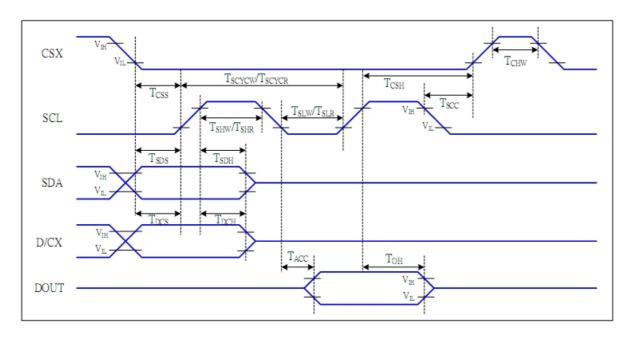


8. Interface Pins Definition

No.	Symbol	Function
1	GND	Ground
2	LCD_RST	This signal will reset the device and it must be applied to properly initialize the
	LOD_NOT	chip.Signal is active low.
3	LCD_SCL	Serial interface clock signal.
4	GND	Ground
5	LCD_CS	Chip selection signal.
6	LCD_SDA	Serial input data signal.
7	LCD_SDO	Serial output data signal.
8	GND	Ground
9	VDD	Power supply.
10	LCD_RS	Display data/command selection.
11	LCD_LED+	Backlight driver Anode.
12	LCD_LED-	Backlight driver Cathode.
13	NC	No connected
14	NC	No connected
15	NC	No connected
16	NC	No connected
17	NC	No connected
18	NC	No connected

9. AC Characteristics

9.1. Serial Interface Characteristics (4-line serial):



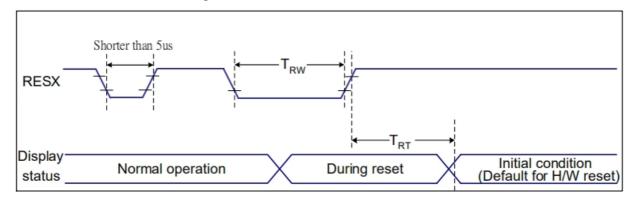
4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, $Ta=25^{\circ}C$

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
	Tcss	Chip select setup time (write)	TBD	-	ns	
	T _{CSH}	Chip select hold time (write)	TBD	-	ns	
CSX	Tcss	Chip select setup time (read)	TBD	-	ns	
	T _{SCC}	Chip select hold time (read)	TBD	-	ns	
	T _{CHW}	Chip select "H" pulse width	TBD	-	ns	
	T _{SCYCW}	Serial clock cycle (Write)	TBD	-	ns	-write command & data
	T _{SHW}	SCL "H" pulse width (Write)	TBD	-	ns	
SCL	T _{SLW}	SCL "L" pulse width (Write)	TBD	-	ns	ram
SCL	T _{SCYCR}	Serial clock cycle (Read)	TBD	-	ns	-read command & data
	T _{SHR}	SCL "H" pulse width (Read)	TBD	-	ns	ram
	T _{SLR}	SCL "L" pulse width (Read)	TBD	-	ns	Idili
D/CX	T _{DCS}	D/CX setup time	TBD	-	ns	
D/CX	T _{DCH}	D/CX hold time	TBD	-	ns	
SDA	T _{SDS}	Data setup time	TBD	-	ns	
(DIN)	T _{SDH}	Data hold time	TBD	-	ns	
DOUT	T _{ACC}	Access time	TBD	TBD	ns	For maximum CL=30pF
DOOT	Тон	Output disable time	TBD	TBD	ns	For minimum CL=8pF

4-line serial Interface Characteristics

9.2. Reset Timing



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

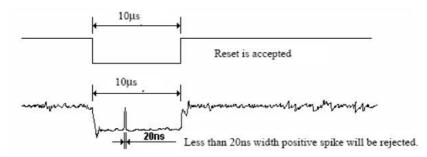
Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	TBD	-	us
RESX	TOT	TDT Deserted		TBD (Note 1, 5)	ms
TRT Reset cancel		-	TBD (Note 1, 6, 7)	ms	

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
 - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
 - 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

10. Quality Assurance

10.1. Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5 Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
- 10.3.2. Customer should provide overall information of non-conforming sample for their complaints.
- 10.3.3. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
- 10.3.4. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.5. Disposition of nonconforming:
- 10.3.6. Non-conforming product over PPM level will be replaced.
- 10.3.7. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

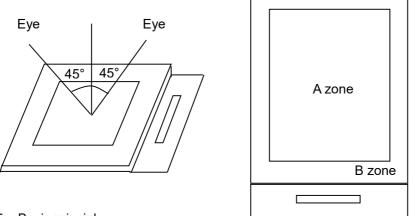
10.4. Agreement Items

Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

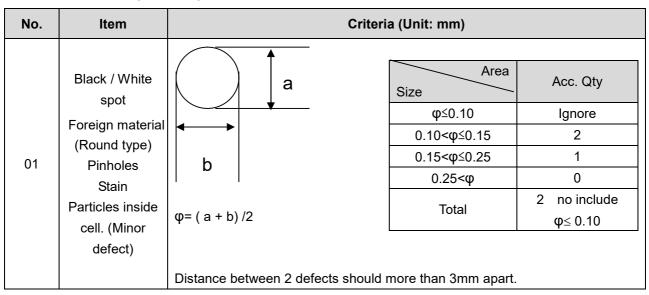
10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
- 10.5.2. The inspection must be under illumination about 1000 1500 lx, and the distance of view must be at 30cm ± 2cm.
- 10.5.3. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.
- 10.5.4. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



- 10.5.5. Basic principle:
- 10.5.6. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.
- 10.5.7. New item must be added on time when it is necessary.

10.6.Inspection Specification



	<u> </u>									
			Display Area	Total						
00		Bright dot	0	0	Note1					
		Dark dot	N≤2	N≤2	Note					
	Electrical Defect	Total dot	N≤2	N≤2						
02	(Minor defect)	Mura	Note 2							
		Remark:	aused by scratch and for	eign object acc	ords to item 1					
		i. Bright dot oa	dised by solution and lor	eigii object acc	ords to item 1.					
03	Black and White line Scratch Foreign material	N L		L						
	(Line type) (Minor defect)	Length	Width	Acc. Qty						
		1	W ≦ 0.03	Ignore						
		L ≦ .5	$0.03 < W \le 0.5$	3						
		L ≦ 2.5	$0.05 < W \le 0.10$	2						
		/	0.1 < W	0						
			2 defects should more e back of the display are		part. Scratches not					
04	Glass Crack (Minor defect)	Crack is potential to enlarge, any type is not allowed.								

	Glass Chipping Pad Area: (Minor defect)							
	(Willion defect)	Length and Width	Acc. Qty					
		c > 3.0, b< 1.0	1					
05		c< 3.0, b< 1.0	3					
		a <glass td="" thic<=""><td>kness</td></glass>	kness					
	b							
	Glass Chipping Rear of Pad Area: (Minor defect)							
	`	Length and Width	Acc. Qty					
00		c > 3.0, b< 1.0	1					
06		c< 3.0, b< 1.0	2					
		c< 3.0, b< 0.5	4					
	b 90 c	a <glass td="" thic<=""><td colspan="6">a<glass td="" thickness<=""></glass></td></glass>	a <glass td="" thickness<=""></glass>					
07	Glass Chipping Except Pad Area: (Minor defect)	Length and Width c > 3.0, b< 1.0 c< 3.0, b< 1.0 c< 3.0, b< 0.5 a <glass th="" thick<=""><th>Acc. Qty 1 2 4 Kness</th></glass>	Acc. Qty 1 2 4 Kness					
08	Glass Corner Chipping: (Minor defect)	Length and Width c < 3.0, b< 3.0 a <glass td="" thick<=""><td>Acc. Qty Ignore kness</td></glass>	Acc. Qty Ignore kness					

	Glass Burr:									
	(Minor defect)									
	,		Leng	yth	Acc. Qty					
			F < '		Ignore					
09	F									
			Glass burr don't affect assemble and module dimension.							
	FPC Defect:									
	(Minor defect)									
	a→	<u>. </u>	10.1 Dent, pinhole	width a <w <="" td=""><td>3.</td></w>	3.					
10	$W \rightarrow \bigcirc$	 ←	(w: circuitry width.)							
		_	10.2 Open circuit is unacceptable.							
	a→	←	10.3 No oxidation, contamination and distortion.							
	ų .									
			Diameter	Acc. Qt	tv					
	Delta de Deltado		φ≤0.20	Ignore						
11	Bubble on Polarizer		0.20 <φ≤0.30	4						
	(Minor defect)		0.30 <φ≤0.50	1						
			0.50 < φ	None						
			Diameter	Acc. Qt	ty					
40	Dent on Polarizer	_	φ≤0.20	Ignore	•					
12	(Minor defect)	<u> </u>	0.20 <φ≤0.30	4						
	,	_	0.30 <φ≤0.50	1						
			0.50 < φ	None						
13	Bezel	13.1 No rust, distortion on the Bezel.								
	23231	13.2 No visible finge	erprints, stains or other contamination.							
		14.1 No distortion o	r contamination on P	CB termina	ıls.					
14	PCB	14.2 All componen	ts on PCB must sa	me as doo	cumented on the					
1-7	1 05	BOM/component layout.								
		14.3 Follow IPC-A-600F.								
15	Soldering	Follow IPC-A-610C	standard							

		The below defects must be rejected.
		16.1 Missing vertical / horizontal segment,
		16.2 Abnormal Display.
	Electrical Defect	16.3 No function or no display.
16	(Major defect)	16.4 Current exceeds product specifications.
	(Major defect)	16.5 LCD viewing angle defect.
		16.6 No Backlight.
		16.7 Dark Backlight.
		16.8 Touch Panel no function.

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

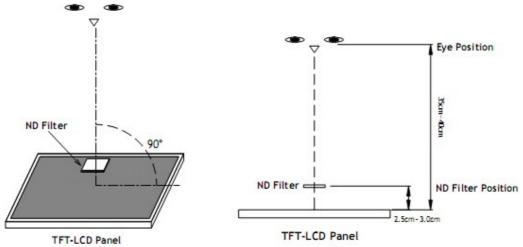
10.8. Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is $350 \text{mm} \pm 50 \text{mm}$.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria	
1	High Temperature Operating	80°C, 96Hrs	2	GB/T2423.2 -2008	
2	Low Temperature Operating	-30°C, 96Hrs	2	GB/T2423.1 -2008	
3	High Humidity Storage	50°C, 90%RH, 96Hrs	2	GB/T2423.3 -2016	
4	High Temperature Storage	85°C, 96Hrs	2	GB/T2423.2 -2008	
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1 -2008	
6	Thermal Cycling Test Storage	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.22 -2012	
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009	
8	Electrical Static Discharge	Air: \pm 4KV 150pF/330 Ω 5 times	2	GB/T17626.2	
	Lieutical otatic discharge	Contact: \pm 2KV 150pF/330 Ω 5 times	2	-2018	
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.7 -2018	

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value.

12. Precautions and Warranty

12.1. Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3. Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4. Metal Pin (Apply to Products with Metal Pins)

- 12.4.1. Pins of LCD and Backlight
 - 12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering
 - 12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

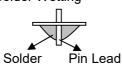
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

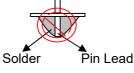
Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



Recommended



Not Recommended

12.4.2. Pins of EL

- 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.
- 12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting



Recommended

Not Recommended

12.4.2.7. The type of the solder iron:



Recommended

Not Recommended

12.4.2.8. Solder Pad



12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Outline Drawing

SYMBOL	GND	LCD_RST	TOS_GOT	GND	CCD_CS	LCD_SDA	OGS-GOT	GND	QQA	LCD_RS	+G37~G07	LCD_LED-	NC	NC	NC	NC	NC	NC
Z Z	-	2	3	4	2	9	7	8	6	10	1	12	13	14	15	16	17	18

